

Silicon PIN Photodiode

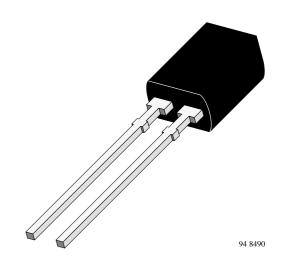
Description

S186P is a high speed and high sensitive PIN photodiode in a flat side view plastic package. The epoxy package itself is an IR filter, spectrally matched to GaAs or GaAs on GaAlAs IR emitters ($\lambda_p \ge 900$ nm).

The large active area combined with a flat case gives a high sensitivity at a wide viewing angle

Features

- Fast response times
- Small junction capacitance
- High radiant sensitivity
- Large radiant sensitive area A=7.5 mm²
- Wide angle of half sensitivity $\varphi = \pm 65^{\circ}$
- Plastic case with IR filter (950 mm)
- Suitable for near infrared radiation



Applications

High speed photo detector

Absolute Maximum Ratings

 $T_{amb} = 25^{\circ}C$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		V_{R}	60	V
Power Dissipation	$T_{amb} \leq 25 ^{\circ}C$	P_{V}	215	mW
Junction Temperature		Tj	100	°C
Storage Temperature Range		T _{stg}	-55+100	°C
Soldering Temperature	$t \le 5 s$	T _{sd}	260	°C
Thermal Resistance Junction/Ambient		R _{thJA}	350	K/W



Basic Characteristics

 $T_{amb} = 25\,^{\circ}C$

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Breakdown Voltage	$I_R = 100 \ \mu A, E = 0$	$V_{(BR)}$	60			V
Reverse Dark Current	$V_R = 10 \text{ V}, E = 0$	I_{ro}		2	30	nA
Diode Capacitance	$V_R = 0 V, f = 1 MHz, E = 0$	C_{D}		70		pF
	$V_R = 3 \text{ V}, f = 1 \text{ MHz}, E = 0$	C_{D}		25	40	pF
Open Circuit Voltage	$E_e = 1 \text{ mW/cm}^2$, $\lambda = 950 \text{ nm}$	V_{o}		350		mV
Short Circuit Current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	I_k		38		μA
Reverse Light Current	$ E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}, $ $V_R = 5 \text{ V} $	I_{ra}	43	45		μΑ
Angle of Half Sensitivity		φ		±65		deg
Wavelength of Peak Sensitivity		$\lambda_{ m p}$		950		nm
Range of Spectral Bandwidth		$\lambda_{0.5}$		8701050		nm
Noise Equivalent Power	V _R =20V, λ=950nm	NEP		4x10 ⁻¹⁴		W/√ Hz
Rise Time	$V_R=10V$, $R_L=1k\Omega$, $\lambda=820$ nm	t _r		100		ns
Fall Time	$V_R=10V$, $R_L=1k\Omega$, $\lambda=820$ nm	t_{f}		100		ns

Typical Characteristics $(T_{amb} = 25^{\circ}C \text{ unless otherwise specified})$

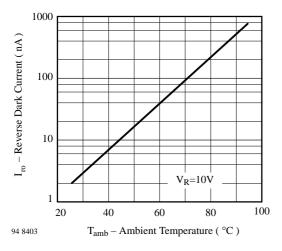


Figure 1. Reverse Dark Current vs. Ambient Temperature

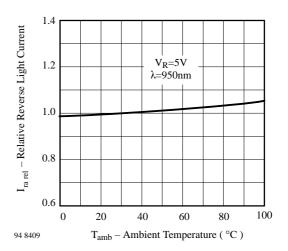


Figure 2. Relative Reverse Light Current vs. Ambient Temperature

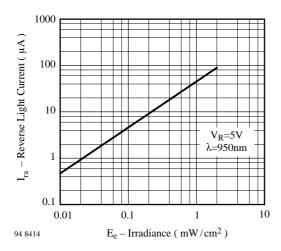


Figure 3. Reverse Light Current vs. Irradiance

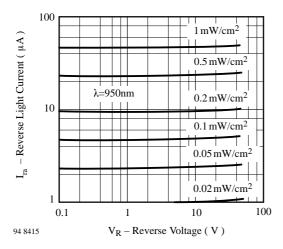


Figure 4. Reverse Light Current vs. Reverse Voltage

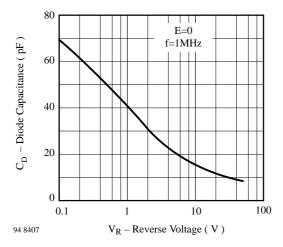


Figure 5. Diode Capacitance vs. Reverse Voltage

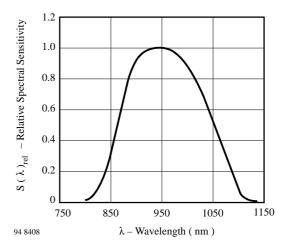


Figure 6. Relative Spectral Sensitivity vs. Wavelength

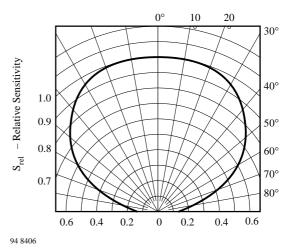
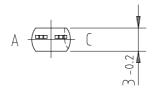
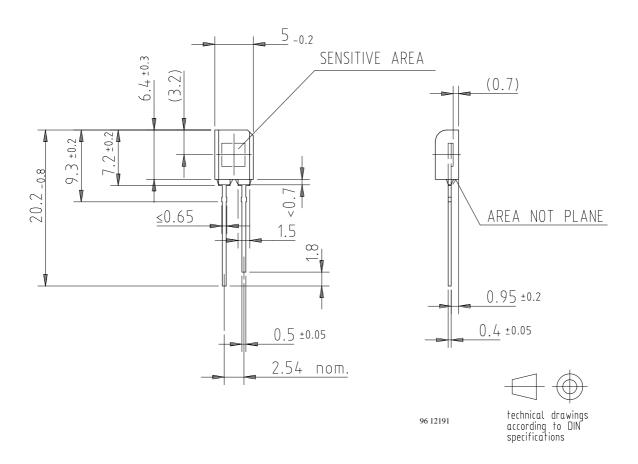


Figure 7. Relative Radiant Sensitivity vs. Angular Displacement



Dimensions in mm







Ozone Depleting Substances Policy Statement

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423